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INFORMATION DISCLOSURE STATEMENT (use several sheets if necessary)		APPLICANT Philip S. Chen, et al.	
		FILING DATE 1/16/2004	GROUP TBA <i>2856</i>

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		PATENT NUMBER	ISSUE DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<i>Jay</i>	AA	10/273,036		Frank DiMeo, et al.			10/17/2002
	AB	6,265,222	6/24/2001	Frank DiMeo, Jr., et al.			
	AC	5,679,576 A	10/21/1997	Kawai, et al.			
	AD	5,612,489 A	3/18/1997	Ragsdale, et al.			
	AE	6,428,713 B1	8/6/2002	Christenson, et al.			
<i>Jay</i>	AF	4,723,438 A	2/9/1988	Adler-Golden, et al.			

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	PUBLICATION DATE	COUNTRY	CLASS	SUBCLAS S	TRANSLATION YES	NO
							X (abstract only)	

OTHER DOCUMENTS (Including Author, Title, Journal-Date, Page Number, Etc.)

<i>Jay</i>	AG	Anderson, B., et al., Semiconductor International, October 1993
	AH	Ed P. Hagenmuller, Inorganic Solid Fluorides, Chemistry and Physics, Academic Press, 1985. (See Information Disclosure Statement Box 1)
	AI	W. Moritz, et al., Sensors and Actuators B 24-25 (1995) 194-196, "Monitoring of HF and F2 using a field-effect sensor"
	AJ	Dr. Shigeru Kurosawa, et al., Fluorine in Coatings II, Paper 33, pgs. 1-8, "Plasma Polymerisation of Fluorine Contained Polycyclic Compounds: Its Application in Chemical Sensors"
	AK	Werner Moritz, et al., The 11th European Conference on Solid State Transducers, Warsaw, Poland, pgs. 111-114, September 21-24, 1997, "Gas Sensors for Fluorine Using Different Semiconductor Substrates"
	AL	Semiconductor International, "Residual Gas Analysis", Oct. 1997, pgs. 94-100
<i>Jay</i>	AM	W. Moritz, et al., "Silicon-Based Sensor for Flourine Gas", American Chemical Society, pags. 119-129.

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EXAMINER	DATE CONSIDERED
<i>Jacque</i>	<i>09/18/05</i>

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.